

Feature

Passive lumped components design
Chebyshev response
1W CW power handling
Parasitic is far away from pass bands

Environmental Specification

Shock	30G
Vibration	20G
Storage conditions	0-40°C, 40% humidity

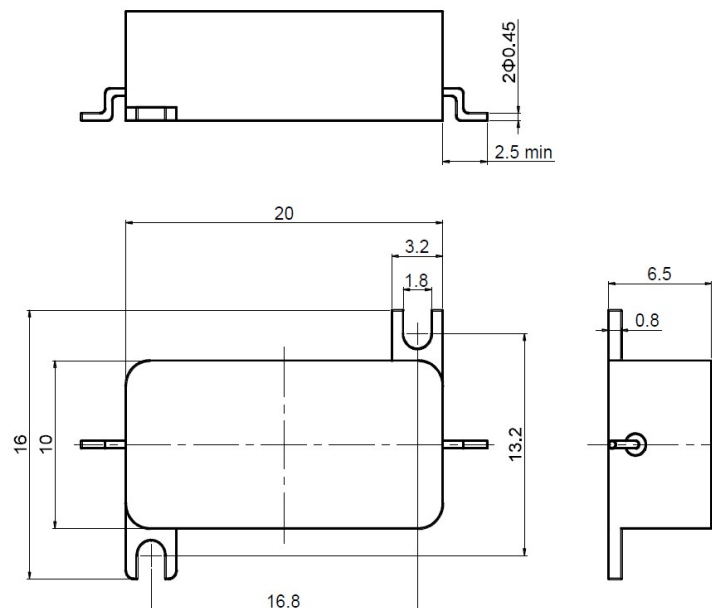
Electrical Specifications ($Z_0=50\Omega$, $-55^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, $P_{in}=-10\text{dBm}$)

Parameter	Specification		
	Min.	Typ.	Max.
Center Frequency (f_0)	-	300MHz	-
1dB Bandwidth	30MHz	35.8MHz	-
Insertion Loss at f_0	-	1.63dB	2.0dB
VSWR @ $f_0 \pm 12\text{MHz}$	-	1.35	1.5
Rejections	200MHz	35dBc	52dBc
	400MHz	35dBc	57dBc
	100MHz	75dBc	78dBc
	500MHz	75dBc	78dBc

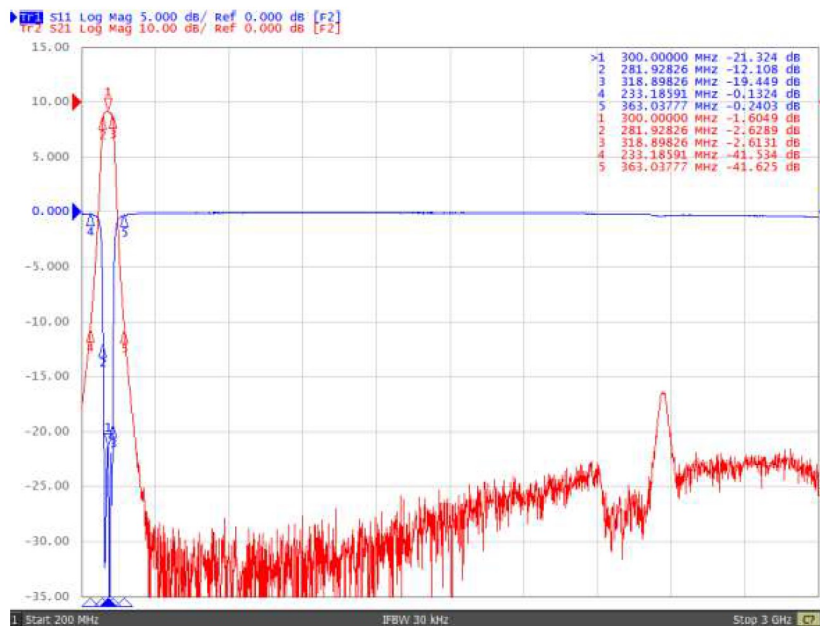
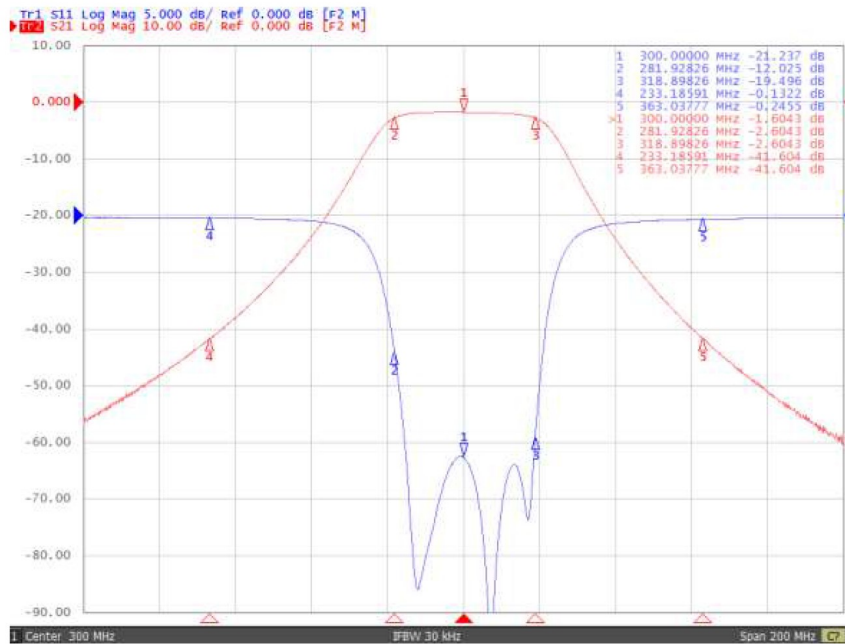
S2P file name: 4MBC-300U30-S1G.s2p

Outline Drawing

(Unit: mm)



Typical Test Curves



Application Instructions

1. The device temperature can't exceed 215°C during assembling and soldering.
2. Recommend using 62Sn36Pb2Ag solder paste.
3. Don't wash the device with solution..